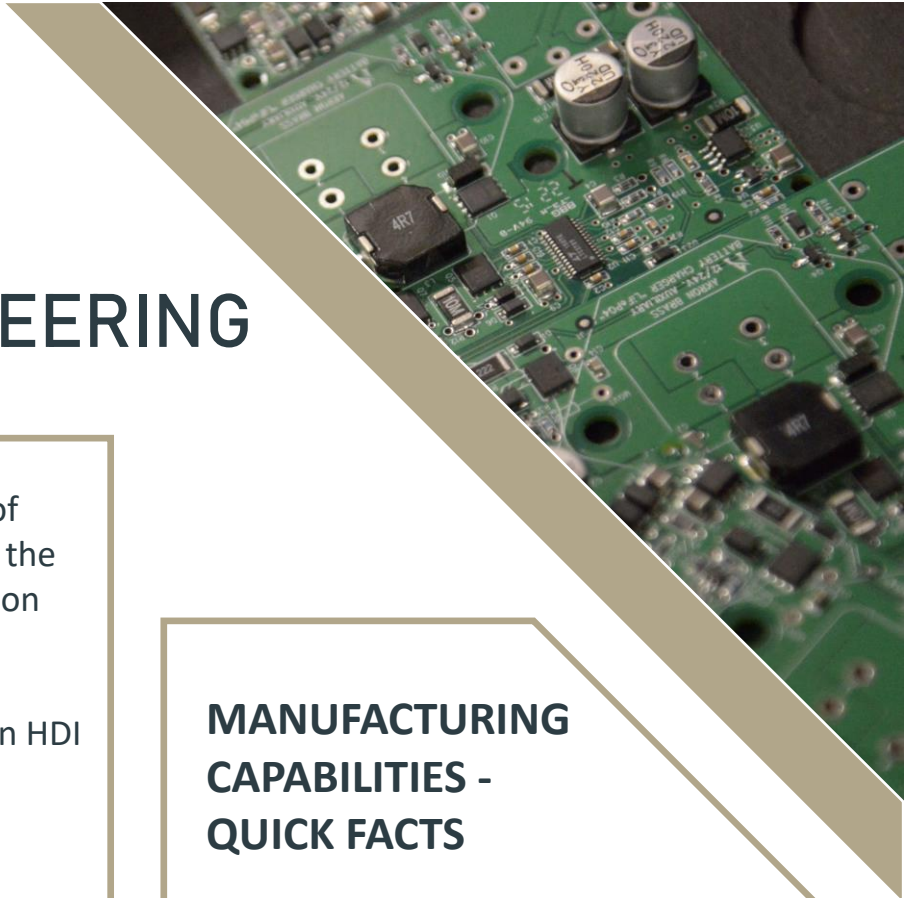


ELECTRONICS - EMBEDDED HARDWARE ENGINEERING



In addition to manufacturing, our team of hardware design engineers can optimize the layout on your board to make it production ready.

Our team includes experienced experts in HDI multi layer PCB stack ups.

EMBEDDED CONTROLS

We design for the following communication protocols

- WiFi
- Bluetooth
- Ethernet
- CAN
- USB
- RS485 / RS232

VOLTAGE RANGES

- 12-48V DC
- 110-220v AC

DESIGN PACKAGES

- Altium Designer
- Mentor Graphics PADs

MANUFACTURING CAPABILITIES - QUICK FACTS

Max PCB size:	330 mm x 250 mm panel
Min PCB size:	50 mm x 30 mm panel (we can fit multiple smaller boards per panel.)
Min. component size:	0201
Min component pitch:	0.4 mm
Max component size:	33.5 mm sq. (can hand place larger components)
BGA placement:	0.25mm min pitch 760+ max # of balls actually placed, software shows larger allowed
3 SMT lines:	Stencil Inspection Placement Reflow Oven AOI

Contact:

W: www.insource-tech.com

E: sales@insource-tech.com

P: (419) 399-3600

